

RL78/G1D

Design of a Reference Antenna

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Introduction

This application note describes an example of the design of a pattern antenna and its characteristics when connected with the RL78/G1D.

Target Device

RL78/G1D (R5F11A)

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1. Overview

This application note describes an example of the design of a pattern antenna.

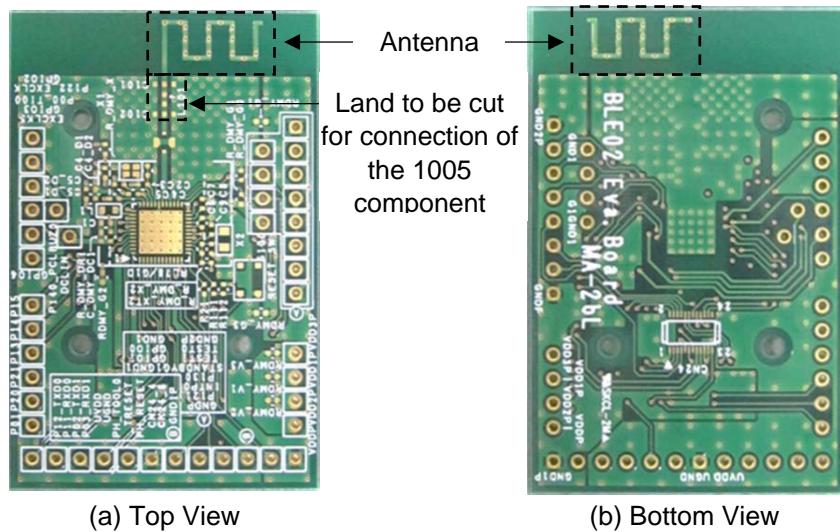
1.1 Related Documents

- RL78/G1D Guidelines for RF Board Design (R01AN2465E)
- RL78/G1D User's Manual: Hardware (R01UH0515E)

2. Configuration of a Reference Antenna

The antenna is a pattern antenna formed on the RL78/G1D evaluation board. Figure 1 consists of photographs of the evaluation board on which the antenna is formed. The antenna is formed as a meandering land pattern on the board, and is connected to a feeder with an impedance of $50\ \Omega$. The land pattern connects the feeder of the antenna with the adjacent GND on the evaluation board. Mounting a 1005 (1-mm long) component in series between the feeder and the GND on the land allows adjustment of the resonance frequency and impedance of the antenna and gives the antenna a wide adjustable range.

Caution To mount the adjusting component, cut the part of the feeder between the land for the ground and for the antenna beforehand.



* The photograph is of the board with no components mounted.

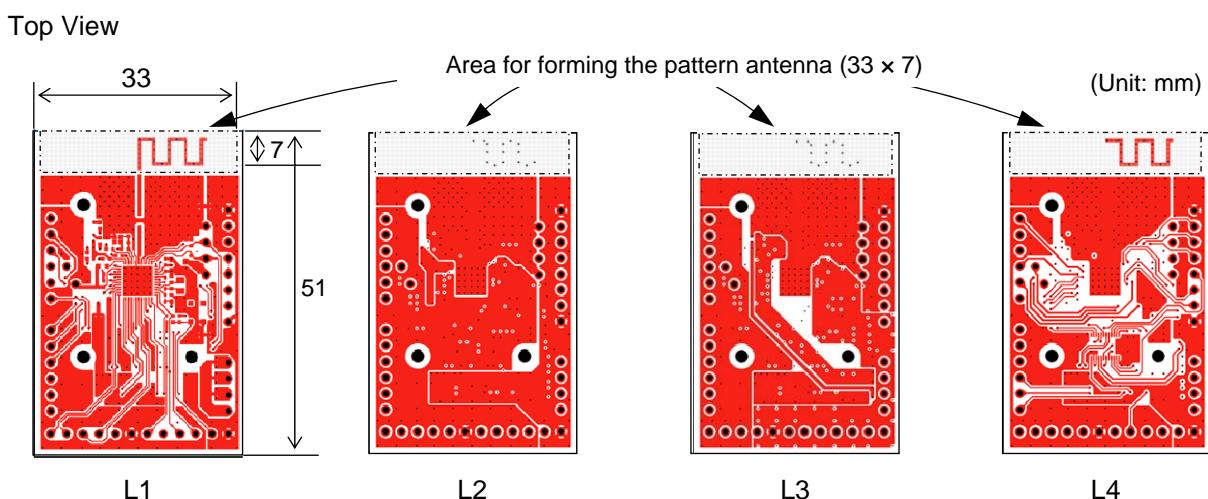
Figure 1 Appearance of the Evaluation Board on which the Reference Antenna is Formed

2.1 Antenna Layout

Figure 2 shows layouts of the patterns formed for the antenna in each layer of the evaluation board.

Size of the evaluation board: $33\text{ mm} \times 51\text{ mm}$

The evaluation board has four layers: L1, L2, L3, and L4. The $33\text{ mm} \times 7\text{ mm}$ area in which the pattern antenna is formed in each layer includes no other pattern. The body of the antenna is formed in layers L1 and L4. The pattern in L1 is connected to the pin for antenna connection ($50\ \Omega$). Multiple via holes connect the pattern in L4 to that in L1.

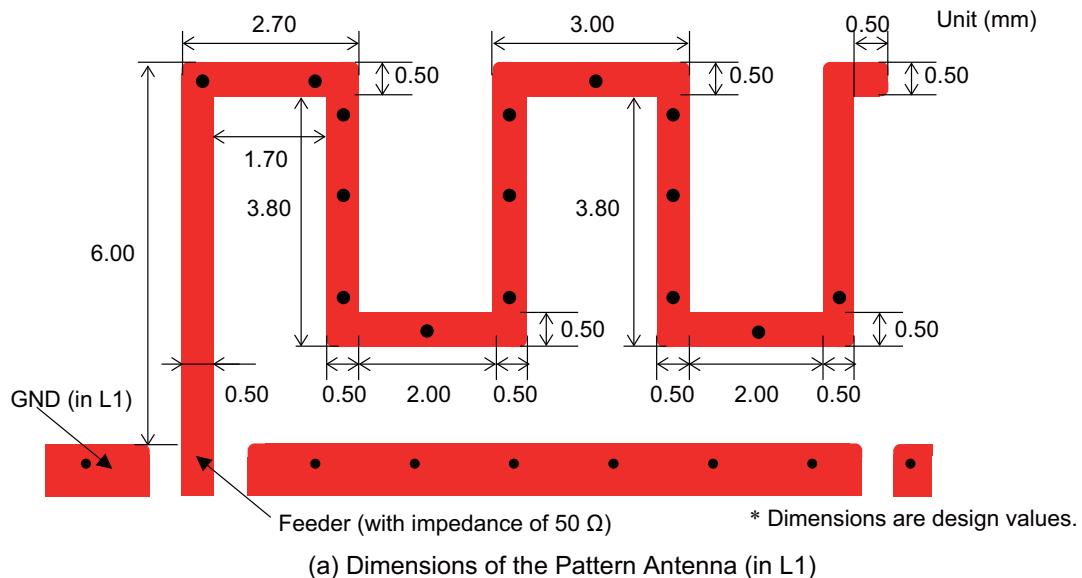


* Dimensions are design values.

Figure 2 Pattern Layouts in Each Layer of the Evaluation Board

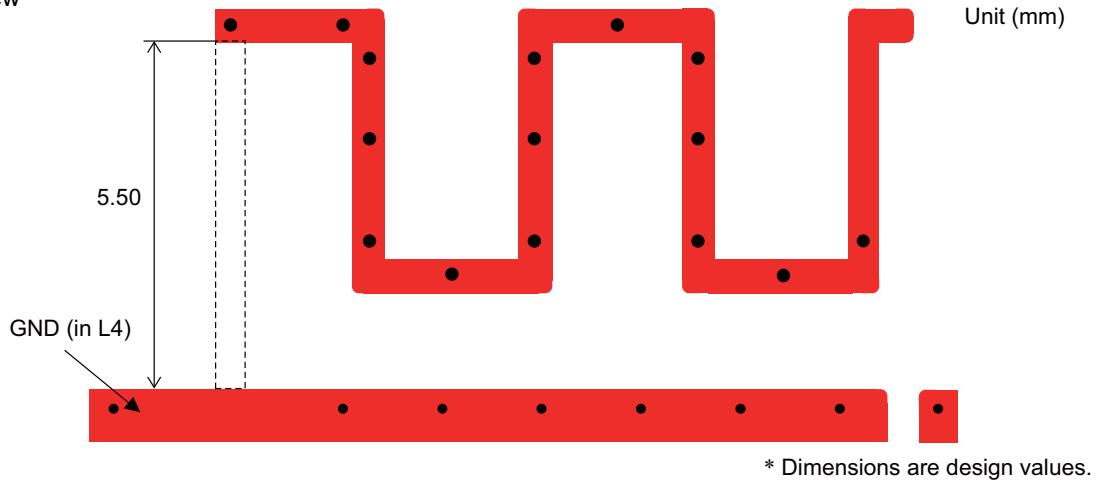
Figure 3 shows dimensions of the antenna.

Top View



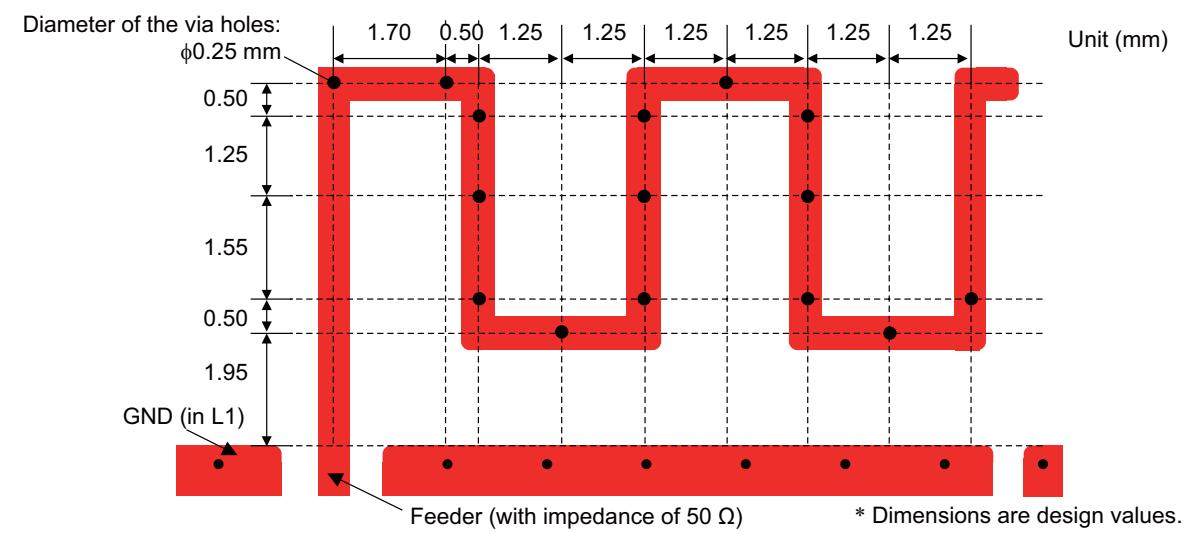
(a) Dimensions of the Pattern Antenna (in L1)

Top View



(b) Dimensions of the Pattern Antenna (in L4)

Top View



(c) Locations of Via Holes

Figure 3 Dimensions of the Reference Antenna

The resonance frequency and impedance of the antenna differ with elements of its surrounding environment, including the size and shape of the board to which the antenna is connected, the wiring patterns on the board, and the housing of the board. Changes to any of these factors require adjustment of the antenna. To start with, adjusting the length of the antenna is more effective than using an adjusting component such as a capacitor or inductor.

To attain the target frequency for the product you are developing, we recommend the following procedure.

<1> Lower the resonance frequency of the antenna by lengthening it relative to the dimensions shown in figure 3.

Caution In lengthening the antenna, repeat the meandering section of the pattern in L1 and L4 so that the wiring in each has the same length.

<2> Shorten the antenna while confirming that the resonance frequency is still approaching the target value.

Caution Shorten the patterns for the antenna in L1 and L4 from the end of the meandering pattern so that the wiring in each layer has the same length.

2.2 Layer Configuration of the Printed Circuit Board

The layer configuration of the printed circuit board including the antenna and chip-evaluation sections is given below.

- Board configuration

Four wiring layers

Configuration	Thickness (mm)
Resist	0.030
Cu (L1)	0.043
PP	0.280
Cu (L2)	0.035
Core material	0.830
Cu (L3)	0.035
PP	0.280
Cu (L4)	0.043
Resist	0.030

* Dimensions are design values.

Figure 4 Layer Configuration of the Board

- Board material
MCL-E-67 (FR4) manufactured by Hitachi Chemical Co., Ltd.
- Thickness
Board: 1.6 mm
Wiring:
 - L1, L4 : Cu 43 μ m
 - L2, L3 : Cu 35 μ m

Figure 4 shows the layer configuration and thicknesses of each layer.

3. Antenna Characteristics

This section describes the voltage standing wave ratio (VSWR) and emission characteristics of the antenna.

In the measurements, a 1.8-pF capacitor (1005-sized package) is mounted as the adjusting component (A in the figure below) on the evaluation board, and is semi-rigidly attached to the feeder.

Top View

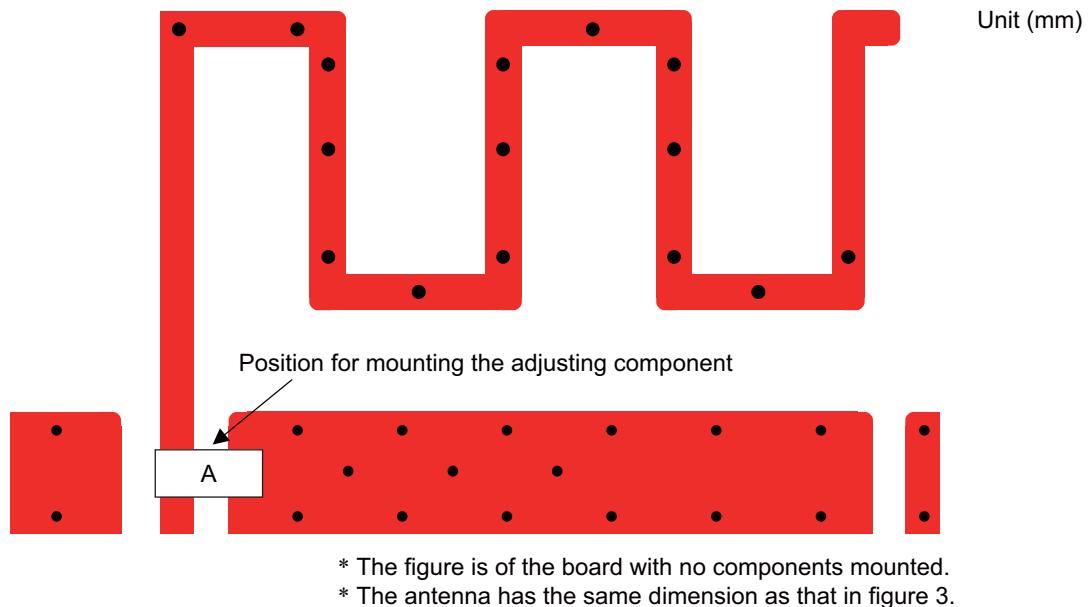


Figure 5 Position for Mounting the Adjusting Component

3.1 VSWR

The results for measurement of the VSWR are given in figure 6. The measurements were made by using a network analyzer in a shield room.

The antenna satisfies $VSWR \leq 2$ over a bandwidth of 115 MHz, including the band from 2400 MHz to 2484 MHz stipulated in the Bluetooth v. 4.1 specification (the section on low-energy single mode).

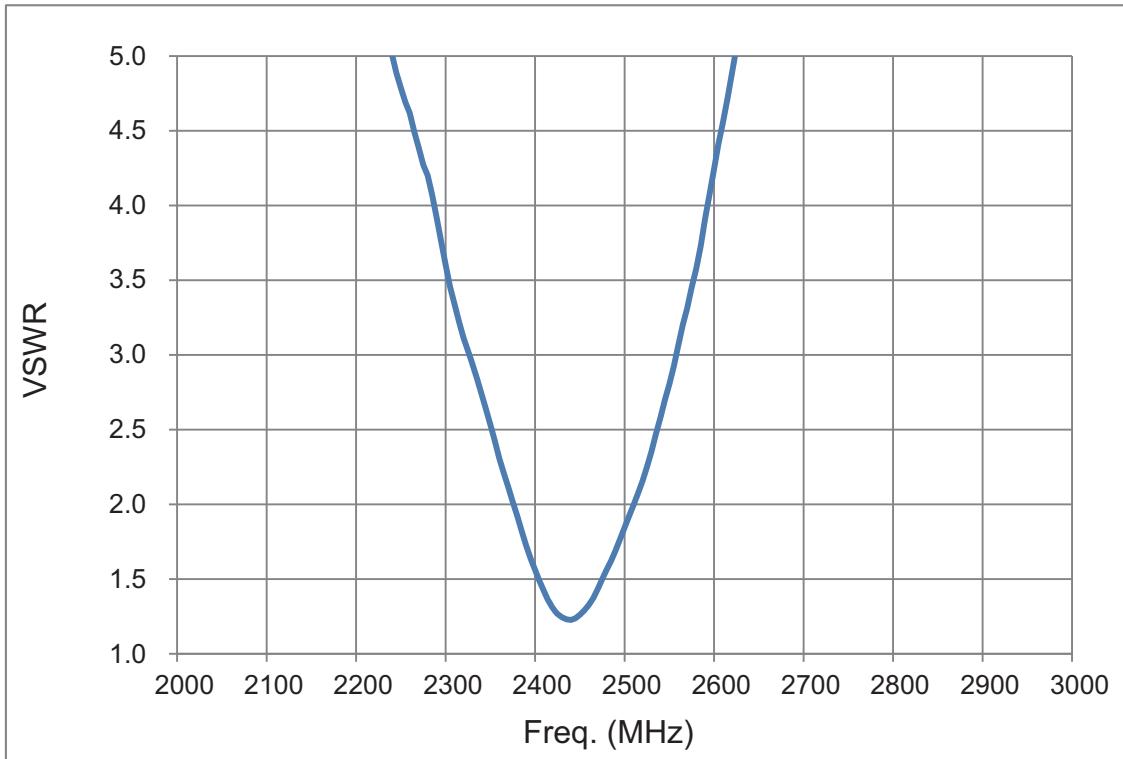
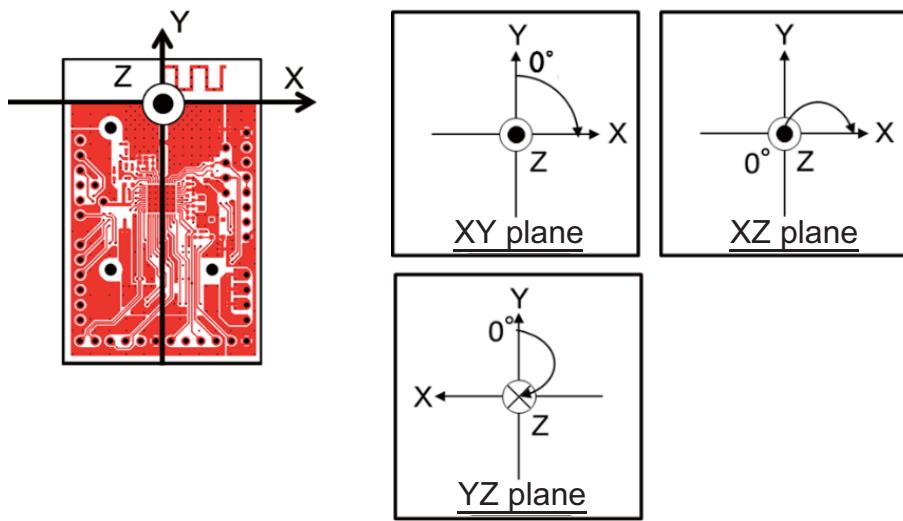


Figure 6 VSWR of the Reference Antenna

3.2 Emission Characteristics

Figure 7 shows the coordinate axes, the positions where rotation starts (0°), and the directions of rotation. The coordinate axes are defined on the basis of the top view of the evaluation board as shown in figure 7(a). The positions where rotation starts (0°) and its directions in obtaining the emission patterns in each plane are defined as shown in figure 7(b).

Top View



(a) Coordinate Axes

(b) Positions where Rotation Starts (0°) and its Directions

Figure 7 Coordinate Axes and Directions of Rotation for Obtaining the Emission Patterns

Table 1 shows the emission patterns and average gains measured with the antennas separated by 3 m from each other in a six-surface radio-wave-dark room. The measurements were made in three planes: XY, XZ, and YZ.

Table 1 Emission Patterns of the Reference Antenna and Average Gains

Item	XY Plane (Horizontally Polarized Wave)	XZ Plane (Vertically Polarized Wave)	YZ Plane (Horizontally Polarized Wave)
Emission patterns of the reference antenna	XY_2440 MHz 	XZ_2440 MHz 	YZ_2440 MHz
Average gain	-2.30 dBi	-1.79 dBi	-2.30 dBi

Caution The values of the adjusting component and for the antenna characteristics in this application note are for reference. They are not guaranteed values. Since the characteristics will differ with the conditions of mounting and the surrounding environment, make the required adjustments for the needs of your actual application.

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Revision Record	RL78/G1D Application Note
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Rev.	Date	Description	
		Page	Summary
0.90	Mar 19, 2015	—	First edition issued

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- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

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4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

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Renesas Electronics America Inc.

2801 Scott Boulevard Santa Clara, CA 95050-2549, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited

9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3
Tel: +1-905-237-2004

Renesas Electronics Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.

Room 1709, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100191, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.

Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, P. R. China 200333
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited

Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2265-6688, Fax: +852 2886-9022

Renesas Electronics Taiwan Co., Ltd.

13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.

80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.

Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics India Pvt. Ltd.

No.777C, 100 Feet Road, HALII Stage, Indiranagar, Bangalore, India
Tel: +91-80-67208700, Fax: +91-80-67208777

Renesas Electronics Korea Co., Ltd.

12F., 234 Teheran-ro, Gangnam-Gu, Seoul, 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141